# MMBTA63LT1G, MMBTA64LT1G, SMMBTA64LT1G

# **Darlington Transistors**

# **PNP Silicon**

## **Features**

- AEC-Q101 Qualified and PPAP Capable
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant\*

## **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector - Emitter Voltage	V <sub>CES</sub>	-30	Vdc
Collector - Base Voltage	V <sub>CBO</sub>	-30	Vdc
Emitter - Base Voltage	V <sub>EBO</sub>	-10	Vdc
Collector Current - Continuous	I <sub>C</sub>	-500	mAdc

## THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board, (Note 1) T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	225 1.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate, (Note 2) T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	300 2.4	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- 1.  $FR-5 = 1.0 \times 0.75 \times 0.062$  in.
- 2. Alumina = 0.4 x 0.3 x 0.024 in. 99.5% alumina.

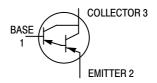


# ON Semiconductor®

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SOT-23 (TO-236) **CASE 318** STYLE 6



# **MARKING DIAGRAM**



2x = Device Code

x = U for MMBTA63LT1G x = V for MMBTA64LT1G

SMMBTA64LT1G

= Date Code\*

= Pb-Free Package

(Note: Microdot may be in either location)

\*Date Code orientation and/or overbar may vary depending upon manufacturing location.

## **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MMBTA63LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel
MMBTA64LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel
SMMBTA64LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# MMBTA63LT1G, MMBTA64LT1G, SMMBTA64LT1G

# **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector – Emitter Breakdown Voltage ( $I_C = -100 \mu Adc$ )	V <sub>(BR)</sub> CEO	-30	-	Vdc
Collector Cutoff Current (V <sub>CB</sub> = -30 Vdc)	I <sub>CBO</sub>	-	-100	nAdc
Emitter Cutoff Current (V <sub>EB</sub> = -10 Vdc)	I <sub>EBO</sub>	-	-100	nAdc
ON CHARACTERISTICS				
DC Current Gain (Note 3) $ \begin{aligned} &(I_C=-10 \text{ mAdc, V}_{CE}=-5.0 \text{ Vdc}) \\ &\text{MMBTA63} \\ &(I_C=-10 \text{ mAdc, V}_{CE}=-5.0 \text{ Vdc}) \\ &\text{MMBTA64, SMMBTA64} \\ &(I_C=-100 \text{ mAdc, V}_{CE}=-5.0 \text{ Vdc}) \\ &\text{MMBTA63} \\ &(I_C=-100 \text{ mAdc, V}_{CE}=-5.0 \text{ Vdc}) \\ &\text{MMBTA64, SMMBTA64} \end{aligned} $	h <sub>FE</sub>	5,000 10,000 10,000 20,000		
Collector – Emitter Saturation Voltage ( $I_C = -100 \text{ mAdc}$ , $I_B = -0.1 \text{ mAdc}$ )	V <sub>CE(sat)</sub>	-	-1.5	Vdc
Base – Emitter On Voltage ( $I_C = -100 \text{ mAdc}$ , $V_{CE} = -5.0 \text{ Vdc}$ )	V <sub>BE(on)</sub>	_	-2.0	Vdc
SMALL-SIGNAL CHARACTERISTICS				
Current – Gain – Bandwidth Product $(I_C = -10 \text{ mAdc}, V_{CE} = -5.0 \text{ Vdc}, f = 100 \text{ MHz})$		125	_	MHz

<sup>3.</sup> Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.

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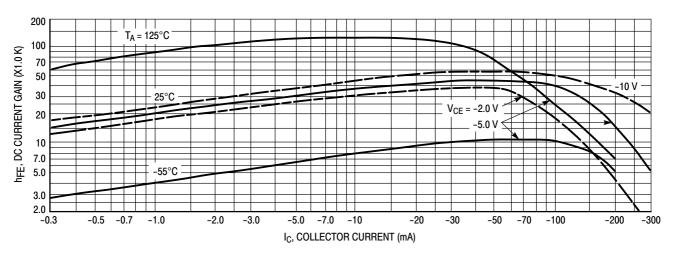


Figure 1. DC Current Gain

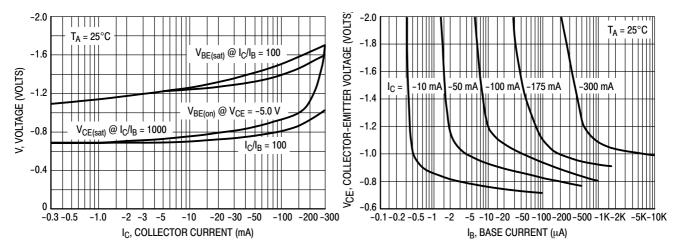


Figure 3. "On" Voltage

Figure 2. Collector Saturation Region

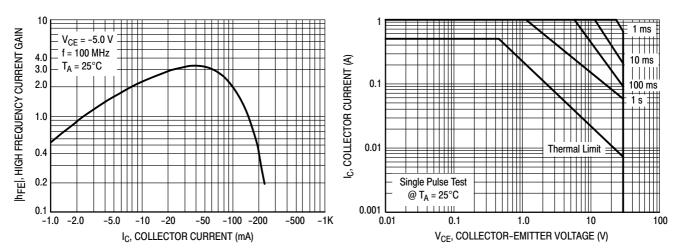


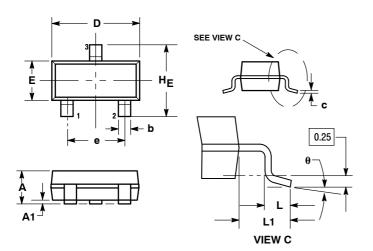
Figure 4. High Frequency Current Gain

Figure 5. Safe Operating Area

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## PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AP** 



- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
  DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH.
- PROTRUSIONS, OR GATE BURRS.

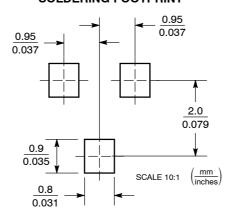
	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
С	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104
A	٥°		10°	٥°		10°

## STYLE 6:

PIN 1. BASE

- **EMITTER**
- COLLECTOR

## **SOLDERING FOOTPRINT**



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